

# DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## BOND OUT CHIP AND METHOD FOR MAKING SAME

the specification of which (check one) X is attached hereto or \_\_\_\_\_ was filed on \_\_\_\_\_ as Application No. \_\_\_\_\_ and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR § 1.56.

I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
			<u>Yes</u>	<u>No</u>
Number	Country	Day/Month/Year Filed	_____	_____
Number	Country	Day/Month/Year Filed	_____	_____

I hereby claim the benefit under 35 U.S.C. § 119(e) of any United States provisional application(s) below.

Application Number	Filing Date
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Application Number	Filing Date
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I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Application Number	Filing Date	Status: Patented, Pending, Abandoned
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Application Number	Filing Date	Status: Patented, Pending, Abandoned
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Fong-Long Lin  
Fong-Long Lin

Inventor's signature Fong-Long Lin Date 12/13/01

Residence 1422 Washo Dr., Fremont, CA 94539

Citizenship USA

Post Office Address \_\_\_\_\_

Full name of inventor Michael S. Briner  
Michael Briner

Inventor's signature Michael S Briner  
Date

Residence 4051 La Mesa Lane, S.J. CA Dec. 14, 2001

Citizenship USA

Post Office Address 4051 La Mesa Lane, San Jose, CA 95124

1003446-422070

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Fong-Long Lin and  
Michael Briner

Group Art Unit: Not Yet Assigned

Serial No.: Not yet assigned

Examiner: Not Yet Assigned

Filed:

Title: **BOND OUT CHIP AND METHOD FOR MAKING SAME**

\* \* \*

POWER OF ATTORNEY BY ASSIGNEE

Assistant Commissioner for Patents  
Box Patent Application  
Washington, D.C. 20231

Sir:

The undersigned, being Assignee of the entire right, title and interest in the above-identified application by virtue of an Assignment, a copy thereof is attached, under 37 C.F.R. §3.71, to prosecute the application to the exclusion of the Inventor(s), and grants Power of Attorney and correspondence address as stated herein.

Silicon Storage Technology, Inc., hereby appoints:

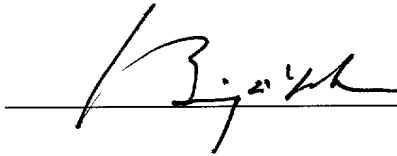
*Barry N. Young (Reg. No. 27,744); Timothy W. Lohse (Reg. No. 35,255); Steven R. Sprinkle (Reg. No. 40,825); Terrance A. Meador (Reg. No. 30,298); June M. Learn (Reg. No. 31,238); William G. Goldman (Reg. No. 42,590); Sheila Kirschenbaum (Reg. No. 44,835); Charles D. Gavrilovich, Jr. (Reg. No. 41,031); Hayward A. Verdun (Reg. No. 43,223); Armando Pastrana, Jr. (Reg. No. 44,997); Lisa A. Haile (Reg. No. 38,347); Richard J. Imbra (Reg. No. 37,643); Mark L. Berrier (Reg. No. 35,066); Mark M. Takahashi (Reg. No. 38,631); James P. Cleary (Reg. No. 45,843); Karl A. Limbach (Reg. No. 18,689); David Alberti (Reg. No. 43,465); Gerald T. Sekimura (Reg. No. 30,103); Eric N. Hoover (Reg. No. 37,355); George C. Limbach (Reg. No. 19,305); Ronald L. Yin (Reg. No. 27,607); Alan A. Limbach (Reg. No. 39,749); Edward B. Weller (Reg. No. 37,468); K. Jun Kim (Reg. No. 43,335); John Adair (Reg. No. 48,828); Peter R. Leal (Reg. No. 24,226); George Meyer (Reg. No. 35,284); Emanuel J. Vacchiano (Reg. No. 38,631); Nan Wu (Reg. No. 43,360)*

Practitioners at Customer Number: 26379 —————>

as attorneys/agents with full power of substitution and revocation to prosecute this application  
and to transact all business in the Patent and Trademark Office connected therewith.

Assignee:  
*Silicon Storage Technology, Inc.*

Date: Dec. 14, 2001



Printed Name: Bing Yeh

Title: President

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